

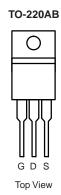
IRF9204PBF-VB Datasheet P-Channel 40 V (D-S) MOSFET

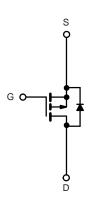
PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^a		
- 40	$0.012 \text{ at V}_{GS} = -10 \text{ V}$	± 65		
	0.014 at V _{GS} = - 4.5 V	± 60		

FEATURES

• Compliant to RoHS Directive 2002/95/EC







P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
Parameter	Symbol	Limit	Unit			
Gate-Source Voltage		V_{GS}	± 40	V		
Continuous Drain Current (T _J = 175 °C)	T _C = 25 °C	-	- 65 ^a			
	T _C = 125 °C	Ι _D	- 62	A		
Pulsed Drain Current	I _{DM}	- 60	A			
Avalanche Current	I _{AR}	- 60				
Repetitive Avalanche Energy ^b	L = 0.1 mH	E _{AR}	180	mJ		
Power Discination	T _C = 25 °C (TO-220AB and TO-263)	D	187 ^d	W		
Power Dissipation	T _A = 25 °C (TO-263) ^c	P_{D}	3.75			
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Limit	Unit	
Junction-to-Ambient	PCB Mount (TO-263) ^c	В	40	°C/W	
Junction-to-Ambient	Free Air (TO-220AB)	R _{thJA}	62.5		
Junction-to-Case	•	R _{thJC}	0.8		

Notes:

- a. Package limited.
- b. Duty cycle \leq 1 %.
- c. When mounted on 1" square PCB (FR-4 material).
- d. See SOA curve for voltage derating.

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 40			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.5		- 1.7	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V _{DS} = - 30 V, V _{GS} = 0 V			- 1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 125 °C			- 50	μA	
		V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 175 °C			- 250		
On-State Drain Current ^a	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 120			Α	
		V _{GS} = - 10 V, I _D = - 30 A		0.012			
Drain-Source On-State Resistance ^a	D	V _{GS} = - 10 V, I _D = - 30 A, T _J = 125 °C		0.010		0	
Diam-Source On-State Resistance	R _{DS(on)}	V _{GS} = - 10 V, I _D = - 30 A, T _J = 175 °C		0.013		Ω	
		V _{GS} = - 4.5 V, I _D = - 20 A		0.014			
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 75 A	20			S	
Dynamic ^b							
Input Capacitance	C _{iss}			9000		pF	
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = - 25 V, f = 1 MHz		1565			
Reversen Transfer Capacitance	C _{rss}			715			
Total Gate Charge ^c	Qg			160	240		
Gate-Source Charge ^c	Q _{gs}	V _{DS} = - 15 V, V _{GS} = - 10 V, I _D = - 75 A		32		nC	
Gate-Drain Charge ^c	Q _{gd}			30			
Turn-On Delay Time ^c	t _{d(on)}			25	40		
Rise Time ^c	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 0.2 \Omega$		225	360		
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong -75 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 2.5 \Omega$		150	240	ns	
Fall Time ^c	t _f			210	340		
Source-Drain Diode Ratings and Cha	racteristics ^b	(T _C = 25 °C)					
Continuous Current	I _S				- 80	۸	
Pulsed Current	I _{SM}				- 240	Α	
Forward Voltage ^a	V _{SD}	I _F = -75 A, V _{GS} = 0 V	A, V _{GS} = 0 V - 1.		- 1.5	V	
Reverse Recovery Time	t _{rr}			55	100	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = - 75 A, dI/dt = 100 A/μs		2.5	5	Α	
Reverse Recovery Charge	Q _{rr}	1		0.07	0.25	μC	

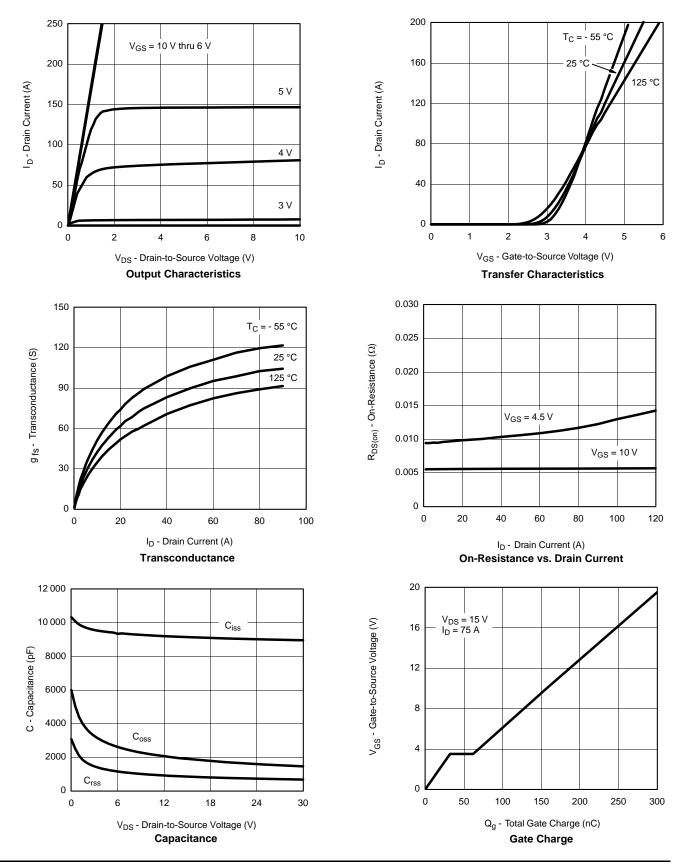
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

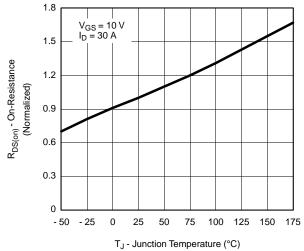


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

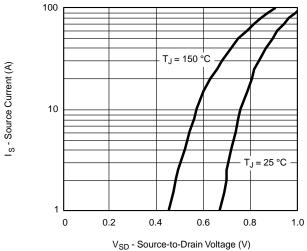




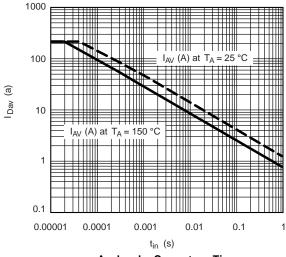
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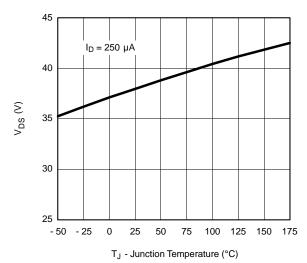
On-Resistance vs. Junction Temperature



Source-Drain Diode Forward Voltage



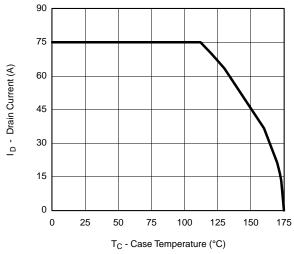
Avalanche Current vs. Time

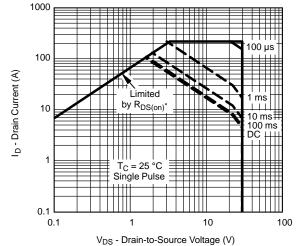


Drain Source Breakdown vs. Junction Temperature

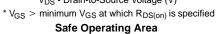


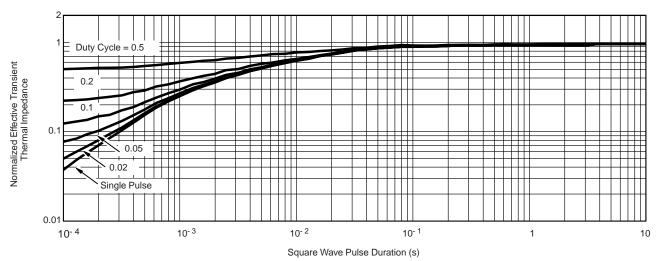
THERMAL RATINGS





Maximum Avalanche and Drain Current vs. Case Temperature





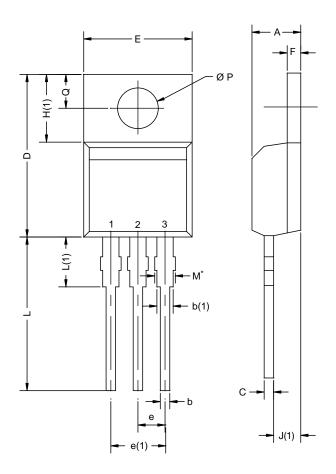
Normalized Thermal Transient Impedance, Junction-to-Case

服务热线:400-655-8788

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TO-220AB



	MILLIM	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
Е	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: X12-0208-Rev. N, 08-Oct-12 DWG: 5471					

Notes

 $^{^{\}star}$ M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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